# MOSFET – SiC Power, Single N-Channel, D2PAK-7L 1200 V, 40 mΩ, 60 A

# 1200 V, 40 III.2, 60 A

# NTBG040N120SC1

#### **Features**

- Typ.  $R_{DS(on)} = 40 \text{ m}\Omega$
- Ultra Low Gate Charge (Typ. Q<sub>G(tot)</sub> = 106 nC)
- Low Effective Output Capacitance (Typ. C<sub>oss</sub> = 139 pF)
- 100% Avalanche Tested
- $T_J = 175^{\circ}C$
- This Device is Pb-Free and is RoHS Compliant

#### **Typical Applications**

- UPS
- DC/DC Converter
- Boost Inverter

#### **MAXIMUM RATINGS** (T<sub>J</sub> = 25°C unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			$V_{DSS}$	V <sub>DSS</sub> 1200	
Gate-to-Source Voltag	ge		$V_{GS}$	+25/-15	V
Recommended Operation Values T <sub>C</sub> < 175°C of Gate – Source Voltage		T <sub>C</sub> < 175°C	$V_{GSop}$	+20/-5	٧
Continuous Drain Current (Note 1)	Steady State	T <sub>C</sub> = 25°C	I <sub>D</sub>	60	Α
Power Dissipation (Note 1)			P <sub>D</sub>	357	W
Continuous Drain Current (Note 1)	Steady State	T <sub>C</sub> = 100°C	I <sub>D</sub>	43	Α
Power Dissipation (Note 1)			P <sub>D</sub>	178	W
Pulsed Drain Current (Note 2) T <sub>A</sub> = 25°C			I <sub>DM</sub>	240	Α
Operating Junction and Storage Temperature Range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C
Source Current (Body Diode)			Is	36	Α
Single Pulse Drain-to-Source Avalanche Energy (I <sub>L</sub> = 34 A <sub>pk</sub> , L = 1 mH) (Note 3)			E <sub>AS</sub>	578	mJ
Maximum Lead Temperature for Soldering, 1/8" from Case for 10 Seconds			TL	300	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

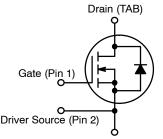
- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 2. Repetitive rating, limited by max junction temperature.
- 3.  $E_{AS}$  of 578 mJ is based on starting  $T_J$  = 25°C; L = 1 mH,  $I_{AS}$  = 34 A,  $V_{DD}$  = 120 V,  $V_{GS}$  = 18 V.



#### ON Semiconductor®

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V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub> MAX	I <sub>D</sub> MAX
1200 V	56 mΩ @ 20 V	60 A



Power Source (Pins 3, 4, 5, 6, 7)

#### **N-CHANNEL MOSFET**



D2PAK-7L CASE 418BJ

#### **MARKING DIAGRAM**

AYWWZZ NTBG 040120SC1

A = Assembly Location

Y = Year WW = Work Week

ZZ = Lot Traceability

NTBG040120SC1 = Specific Device Code

#### **ORDERING INFORMATION**

See detailed ordering and shipping information on page 6 of this data sheet.

**Table 1. THERMAL CHARACTERISTICS** 

Parameter	Symbol	Max	Units
Thermal Resistance Junction-to-Case (Note 1)	$R_{ heta JC}$	0.42	°C/W
Thermal Resistance Junction-to-Ambient (Note 1)	$R_{ hetaJA}$	40	°C/W

Table 2. ELECTRICAL CHARACTERISTICS (T<sub>J</sub> = 25°C unless otherwise stated)

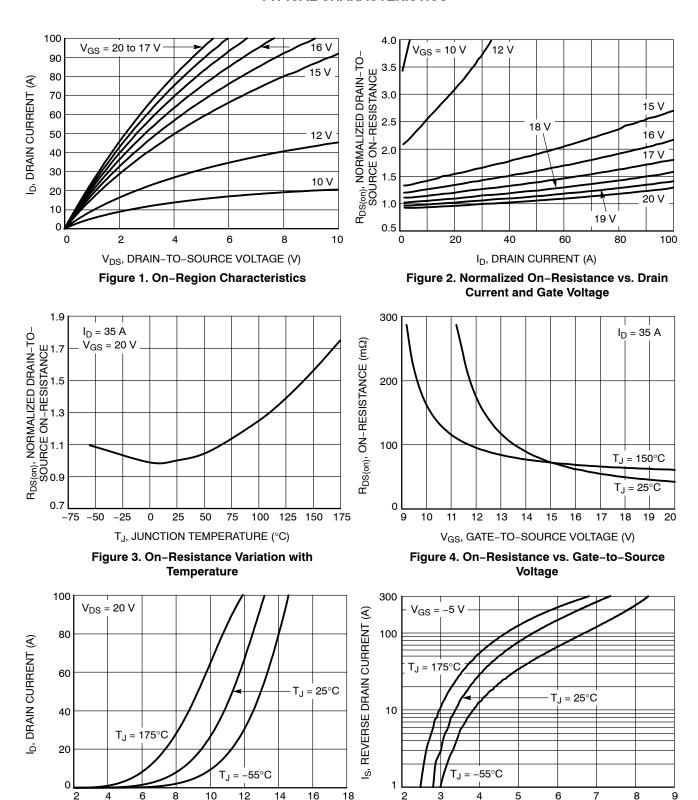
Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS							
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0 \	/, I <sub>D</sub> = 1 mA	1200			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V <sub>(BR)DSS</sub> /T <sub>J</sub>	I <sub>D</sub> = 1 mA, refer to 25°C			0.45		V/°C
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V T <sub>J</sub> = 25°C				100	μΑ
		V <sub>DS</sub> = 1200 V	T <sub>J</sub> = 175°C			1	mA
Gate-to-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = +25/-	15 V, V <sub>DS</sub> = 0 V			±1	μΑ
ON CHARACTERISTICS (Note 2)					•	•	
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{GS} = V_{DS}$	s, I <sub>D</sub> = 10 mA	1.8	3	4.3	V
Recommended Gate Voltage	V <sub>GOP</sub>			-5		+20	V
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 20 V, I <sub>D</sub> :	= 35 A, T <sub>J</sub> = 25°C		40	56	mΩ
		V <sub>GS</sub> = 20 V, I <sub>D</sub> =	35 A, T <sub>J</sub> = 175°C		71	100	mΩ
Forward Transconductance	9FS	V <sub>DS</sub> = 20 V, I <sub>D</sub> = 35 A			20		S
CHARGES, CAPACITANCES & GATE RESI	STANCE				-	•	
Input Capacitance	C <sub>ISS</sub>	V <sub>GS</sub> = 0 V, f = 1 MHz, V <sub>DS</sub> = 800 V			1789		pF
Output Capacitance	C <sub>OSS</sub>				139		
Reverse Transfer Capacitance	C <sub>RSS</sub>				12.5		
Total Gate Charge	Q <sub>G(TOT)</sub>	$V_{GS} = -5/20 \text{ V}, V_{DS} = 600 \text{ V},$ $I_{D} = 47 \text{ A}$			106		nC
Threshold Gate Charge	Q <sub>G(TH)</sub>				18		
Gate-to-Source Charge	$Q_{GS}$				34		
Gate-to-Drain Charge	$Q_{GD}$				26		
Gate-Resistance	$R_{G}$	f = 1 MHz			2		Ω
SWITCHING CHARACTERISTICS			•				
Turn-On Delay Time	t <sub>d(ON)</sub>	$V_{GS} = -5/20$	V, V <sub>DS</sub> = 800 V,		17	30	ns
Rise Time	t <sub>r</sub>		$R_G = 4.7 \Omega$ , ive Load		20	36	
Turn-Off Delay Time	t <sub>d(OFF)</sub>				30	48	1
Fall Time	t <sub>f</sub>				9	18	
Turn-On Switching Loss	E <sub>ON</sub>				366		μJ
Turn-Off Switching Loss	E <sub>OFF</sub>				200		
Total Switching Loss	E <sub>TOT</sub>				566		
DRAIN-SOURCE DIODE CHARACTERISTI	cs						
Continuous Drain-Source Diode Forward Current	I <sub>SD</sub>	V <sub>GS</sub> = -5	V, T <sub>J</sub> = 25°C			36	Α
Pulsed Drain-Source Diode Forward Current (Note 2)	I <sub>SDM</sub>	V <sub>GS</sub> = −5	V, T <sub>J</sub> = 25°C			240	Α
Forward Diode Voltage	$V_{SD}$	$V_{GS} = -5 \text{ V}, I_{SD} = 17.5 \text{ A}, T_{J} = 25^{\circ}\text{C}$			3.7		V

Table 2. ELECTRICAL CHARACTERISTICS (T<sub>.1</sub> = 25°C unless otherwise stated)

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit	
DRAIN-SOURCE DIODE CHARACTERISTICS							
Reverse Recovery Time	t <sub>RR</sub>	$V_{GS} = -5/20 \text{ V}, I_{SD} = 47 \text{ A},$ $dI_{S}/dt = 1000 \text{ A}/\mu\text{s}$		24		ns	
Reverse Recovery Charge	Q <sub>RR</sub>			124.8		nC	
Reverse Recovery Energy	E <sub>REC</sub>			8.4		μJ	
Peak Reverse Recovery Current	I <sub>RRM</sub>			10.4		Α	
Charge time	Ta			12.4		ns	
Discharge time	Tb			11.6		ns	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

#### **TYPICAL CHARACTERISTICS**



V<sub>GS</sub>, GATE-TO-SOURCE VOLTAGE (V) Figure 5. Transfer Characteristics

 $V_{SD}$ , BODY DIODE FORWARD VOLTAGE (V) Figure 6. Diode Forward Voltage vs. Current

#### **TYPICAL CHARACTERISTICS**

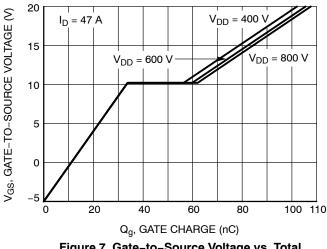


Figure 7. Gate-to-Source Voltage vs. Total Charge

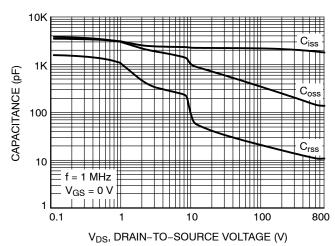


Figure 8. Capacitance vs. Drain-to-Source Voltage

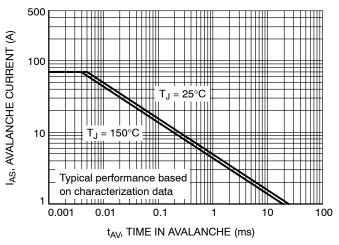


Figure 9. Unclamped Inductive Switching Capability

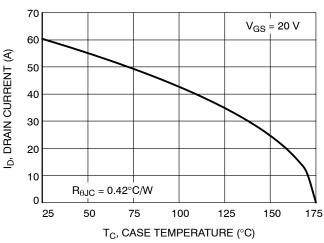


Figure 10. Maximum Continuous Drain Current vs. Case Temperature

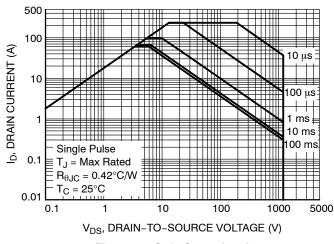


Figure 11. Safe Operating Area

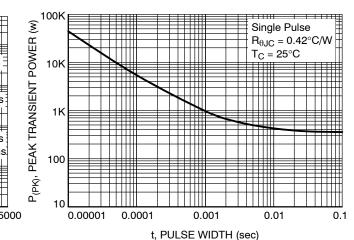


Figure 12. Single Pulse Maximum Power Dissipation

#### **TYPICAL CHARACTERISTICS**

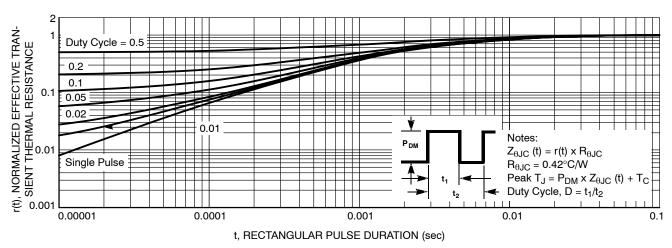


Figure 13. Junction-to-Ambient Transient Thermal Response Curve

#### **DEVICE ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NTBG040N120SC1	D2PAK-7L	800 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Α

D

aaa | B | A |M

3.20 MIN

E1

#### D<sup>2</sup>PAK7 (TO-263-7L HV) CASE 418BJ **ISSUE B**

**DATE 16 AUG 2019** 

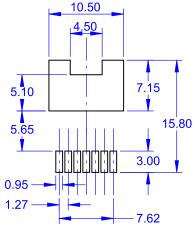
#### NOTES:

- A. PACKAGE CONFORMS TO JEDEC TO-263 VARIATION CB EXCEPT WHERE NOTED. B. ALL DIMENSIONS ARE IN MILLIMETERS.
- OUT OF JEDEC STANDARD VALUE.

  D. DIMENSION AND TOLERANCE AS PER ASME Y14.5-2009.

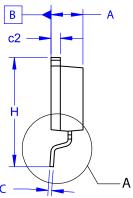
  E. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.

DIM	MIL	LIMETER	S
DIM	MIN	NOM	MAX
Α	4.30	4.50	4.70
<b>A</b> 1	0.00	0.10	0.20
b2	0.60	0.70	0.80
b	0.51	0.60	0.70
С	0.40	0.50	0.60
c2	1.20	1.30	1.40
D	9.00	9.20	9.40
D1	6.15	6.80	7.15
Е	9.70	9.90	10.20
E1	7.15	7.65	8.15
е	~	1.27	~
Н	15.10	15.40	15.70
L	2.44	2.64	2.84
L1	1.00	1.20	1.40
L3	~	0.25	~
aaa	~	~	0.25



#### LAND PATTERN RECOMMENDATION





# **GENERIC MARKING DIAGRAM\***

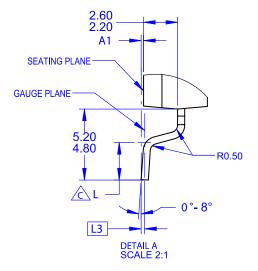
D1



XXXX = Specific Device Code = Assembly Location

= Year WW = Work Week G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "=", may or may not be present. Some products may not follow the Generic Marking.



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